

IRG4IBC20KDPbF

INSULATED GATE BIPOLEAR TRANSISTOR WITH ULTRAFAST SOFT RECOVERY DIODE

Short Circuit Rated
UltraFast IGBT

Features

- High switching speed optimized for up to 25kHz with low $V_{CE(on)}$
- Short Circuit Rating 10 μ s @ 125°C, $V_{GE} = 15V$
- Generation 4 IGBT design provides tighter parameter distribution and higher efficiency than previous generation
- IGBT co-packaged with HEXFRED™ ultrafast, ultra-soft-recovery anti-parallel diodes for use in bridge configurations
- Industry standard TO-220 FULLPAK
- Lead-Free

Benefits

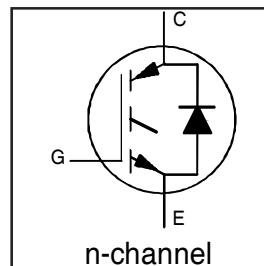
- Generation 4 IGBTs offer highest efficiencies available maximizing the power density of the system
- IGBTs optimized for specific application conditions
- HEXFRED™ diodes optimized for performance with IGBTs. Minimized recovery characteristics reduce noise EMI
- Designed to exceed the power handling capability of equivalent industry-standard IGBTs

Absolute Maximum Ratings

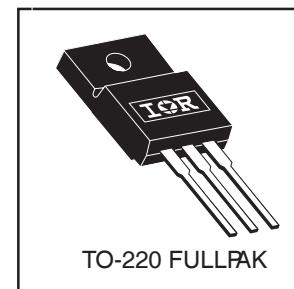
	Parameter	Max.	Units
V_{CES}	Collector-to-Emitter Voltage	600	V
$I_C @ T_C = 25^\circ C$	Continuous Collector Current	11.5	
$I_C @ T_C = 100^\circ C$	Continuous Collector Current	6.3	
I_{CM}	Pulsed Collector Current ①	23	A
I_{LM}	Clamped Inductive Load Current ②	24	
$I_F @ T_C = 100^\circ C$	Diode Continuous Forward Current	6.3	
I_{FM}	Diode Maximum Forward Current	24	
t_{sc}	Short Circuit Withstand Time	10	μ s
V_{ISOL}	RMS Isolation Voltage, Terminal to Case, $t = 1$ min	2500	V
V_{GE}	Gate-to-Emitter Voltage	± 20	
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	34	
$P_D @ T_C = 100^\circ C$	Maximum Power Dissipation	14	W
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to +150	$^\circ C$
	Soldering Temperature, for 10 sec.	300 (0.063 in. (1.6mm) from case)	
	Mounting Torque, 6-32 or M3 Screw.	10 lbf•in (1.1 N•m)	

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case - IGBT	—	3.7	
$R_{\theta CS}$	Junction-to-Case - Diode	—	5.5	$^\circ C/W$
$R_{\theta JA}$	Junction-to-Ambient, typical socket mount	—	65	
Wt	Weight	2.0 (0.07)	—	g (oz)



$V_{CES} = 600V$
 $V_{CE(on)} \text{ typ.} = 2.27V$
@ $V_{GE} = 15V, I_C = 6.3A$



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Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(\text{BR})\text{CES}}$	Collector-to-Emitter Breakdown Voltage③	600	—	—	V	$V_{\text{GE}} = 0\text{V}$, $I_C = 250\mu\text{A}$
$\Delta V_{(\text{BR})\text{CES}/\Delta T_J}$	Temperature Coeff. of Breakdown Voltage	—	0.49	—	V/ $^\circ\text{C}$	$V_{\text{GE}} = 0\text{V}$, $I_C = 1.0\text{mA}$
$V_{\text{CE}(\text{on})}$	Collector-to-Emitter Saturation Voltage	—	2.27	2.8	V	$I_C = 9.0\text{A}$ $V_{\text{GE}} = 15\text{V}$
		—	3.01	—		$I_C = 16\text{A}$ See Fig. 2, 5
		—	2.43	—		$I_C = 9.0\text{A}$, $T_J = 150^\circ\text{C}$
$V_{\text{GE}(\text{th})}$	Gate Threshold Voltage	3.0	—	6.0		$V_{\text{CE}} = V_{\text{GE}}$, $I_C = 250\mu\text{A}$
$\Delta V_{\text{GE}(\text{th})/\Delta T_J}$	Temperature Coeff. of Threshold Voltage	—	-10	—	mV/ $^\circ\text{C}$	$V_{\text{CE}} = V_{\text{GE}}$, $I_C = 250\mu\text{A}$
g_{fe}	Forward Transconductance ④	2.9	4.3	—	S	$V_{\text{CE}} = 100\text{V}$, $I_C = 9.0\text{A}$
I_{CES}	Zero Gate Voltage Collector Current	—	—	250	μA	$V_{\text{GE}} = 0\text{V}$, $V_{\text{CE}} = 600\text{V}$
		—	—	1000		$V_{\text{GE}} = 0\text{V}$, $V_{\text{CE}} = 600\text{V}$, $T_J = 150^\circ\text{C}$
V_{FM}	Diode Forward Voltage Drop	—	1.4	1.7	V	$I_C = 8.0\text{A}$ See Fig. 13
		—	1.3	1.6		$I_C = 8.0\text{A}$, $T_J = 150^\circ\text{C}$
I_{GES}	Gate-to-Emitter Leakage Current	—	—	± 100	nA	$V_{\text{GE}} = \pm 20\text{V}$

Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
Q_g	Total Gate Charge (turn-on)	—	34	51	nC	$I_C = 9.0\text{A}$
Q_{ge}	Gate - Emitter Charge (turn-on)	—	4.9	7.4		$V_{\text{CC}} = 400\text{V}$ See Fig.8
Q_{gc}	Gate - Collector Charge (turn-on)	—	14	21		$V_{\text{GE}} = 15\text{V}$
$t_{\text{d}(\text{on})}$	Turn-On Delay Time	—	54	—	ns	$T_J = 25^\circ\text{C}$ $I_C = 9.0\text{A}$, $V_{\text{CC}} = 480\text{V}$ $V_{\text{GE}} = 15\text{V}$, $R_G = 50\Omega$
t_r	Rise Time	—	34	—		
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time	—	180	270		
t_f	Fall Time	—	72	110		
E_{on}	Turn-On Switching Loss	—	0.34	—	mJ	Energy losses include "tail" and diode reverse recovery See Fig. 9,10,14
E_{off}	Turn-Off Switching Loss	—	0.30	—		
E_{ts}	Total Switching Loss	—	0.64	0.96		
t_{sc}	Short Circuit Withstand Time	10	—	—	μs	$V_{\text{CC}} = 360\text{V}$, $T_J = 125^\circ\text{C}$ $V_{\text{GE}} = 15\text{V}$, $R_G = 50\Omega$, $V_{\text{CPK}} < 500\text{V}$
$t_{\text{d}(\text{on})}$	Turn-On Delay Time	—	51	—	ns	$T_J = 150^\circ\text{C}$, See Fig. 10,11,14 $I_C = 9.0\text{A}$, $V_{\text{CC}} = 480\text{V}$ $V_{\text{GE}} = 15\text{V}$, $R_G = 50\Omega$
t_r	Rise Time	—	37	—		
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time	—	220	—		
t_f	Fall Time	—	160	—		
E_{ts}	Total Switching Loss	—	0.85	—	mJ	Energy losses include "tail" and diode reverse recovery
L_E	Internal Emitter Inductance	—	7.5	—	nH	Measured 5mm from package
C_{ies}	Input Capacitance	—	450	—	pF	$V_{\text{GE}} = 0\text{V}$ $V_{\text{CC}} = 30\text{V}$ See Fig. 7 $f = 1.0\text{MHz}$
C_{oes}	Output Capacitance	—	61	—		
C_{res}	Reverse Transfer Capacitance	—	14	—		
t_{rr}	Diode Reverse Recovery Time	—	37	55	ns	$T_J = 25^\circ\text{C}$ See Fig. $T_J = 125^\circ\text{C}$ 14
		—	55	90		$T_J = 25^\circ\text{C}$ See Fig. $T_J = 125^\circ\text{C}$ 15
I_{rr}	Diode Peak Reverse Recovery Current	—	3.5	5.0	A	$T_J = 25^\circ\text{C}$ See Fig. $T_J = 125^\circ\text{C}$ 16
		—	4.5	8.0		$T_J = 25^\circ\text{C}$ See Fig. $T_J = 125^\circ\text{C}$ 17
Q_{rr}	Diode Reverse Recovery Charge	—	65	138	nC	$T_J = 25^\circ\text{C}$ See Fig. $T_J = 125^\circ\text{C}$ 16
		—	124	360		$T_J = 25^\circ\text{C}$ See Fig. $T_J = 125^\circ\text{C}$ 17
$di_{(\text{rec})M}/dt$	Diode Peak Rate of Fall of Recovery During t_b	—	240	—	A/ μs	$T_J = 25^\circ\text{C}$ See Fig. $T_J = 125^\circ\text{C}$ 17
		—	210	—		$T_J = 25^\circ\text{C}$ See Fig. $T_J = 125^\circ\text{C}$ 17

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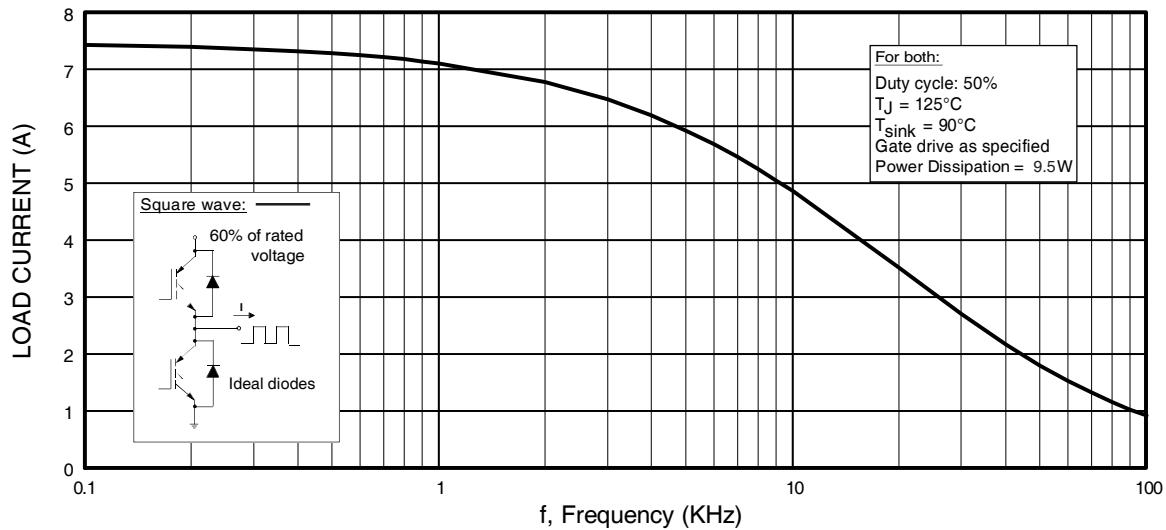


Fig. 1 - Typical Load Current vs. Frequency
(Load Current = I_{RMS} of fundamental)

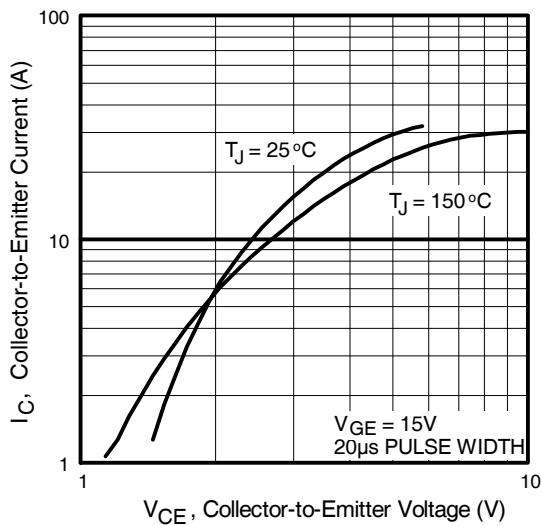


Fig. 2 - Typical Output Characteristics

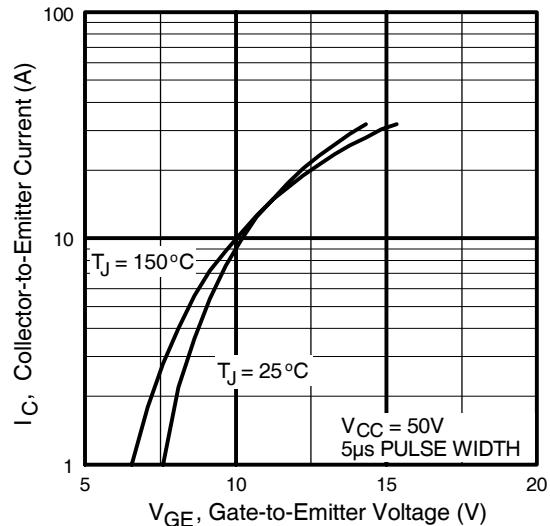


Fig. 3 - Typical Transfer Characteristics

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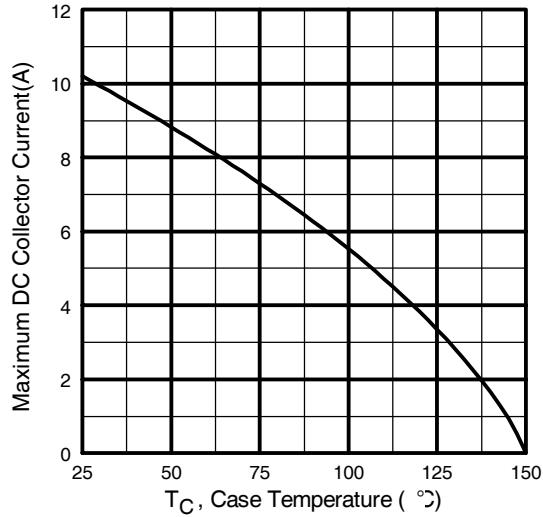


Fig. 4 - Maximum Collector Current vs. Case Temperature

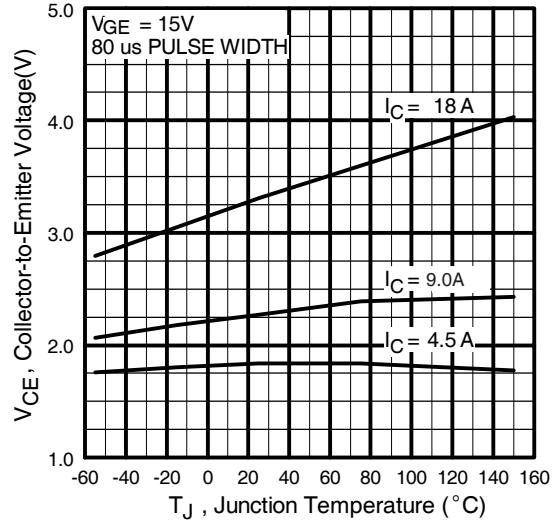


Fig. 5 - Typical Collector-to-Emitter Voltage vs. Junction Temperature

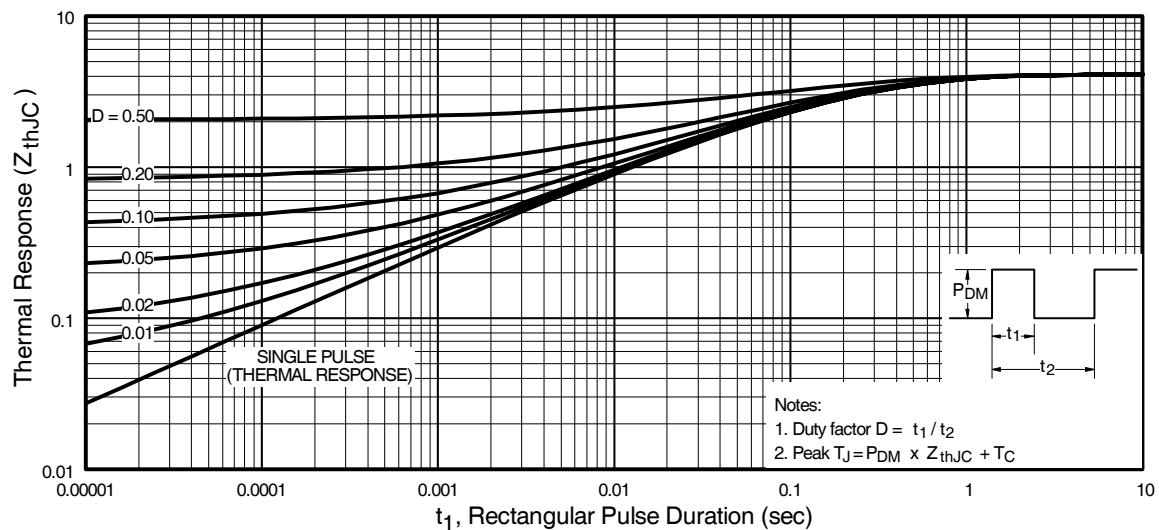


Fig. 6 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

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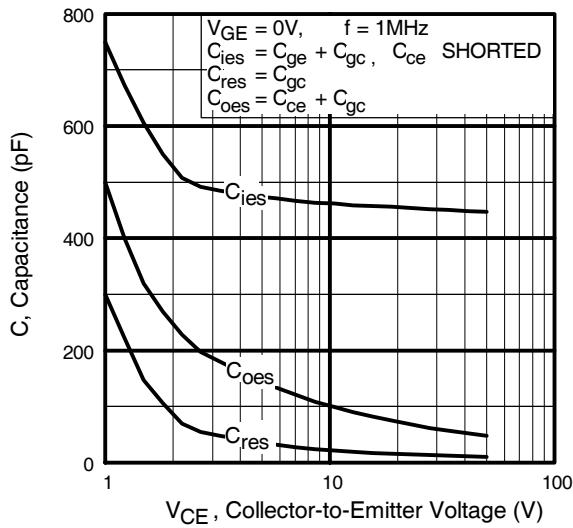


Fig. 7 - Typical Capacitance vs. Collector-to-Emitter Voltage

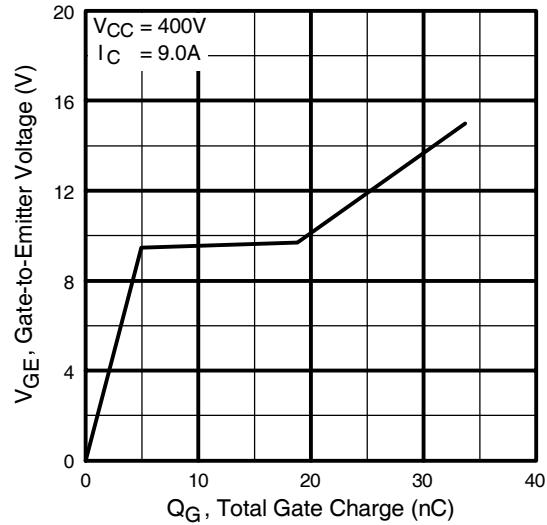


Fig. 8 - Typical Gate Charge vs. Gate-to-Emitter Voltage

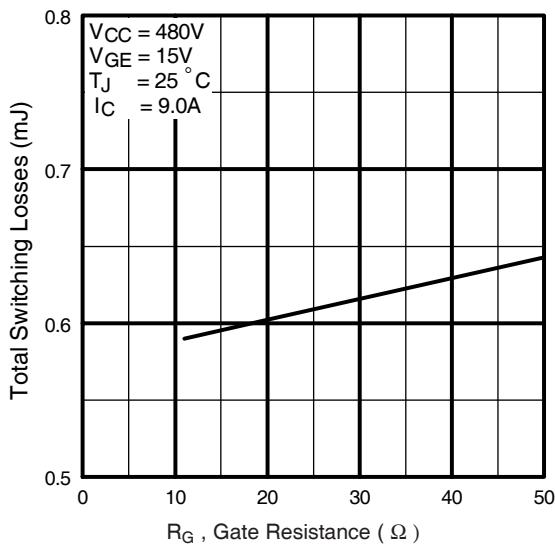


Fig. 9 - Typical Switching Losses vs. Gate Resistance

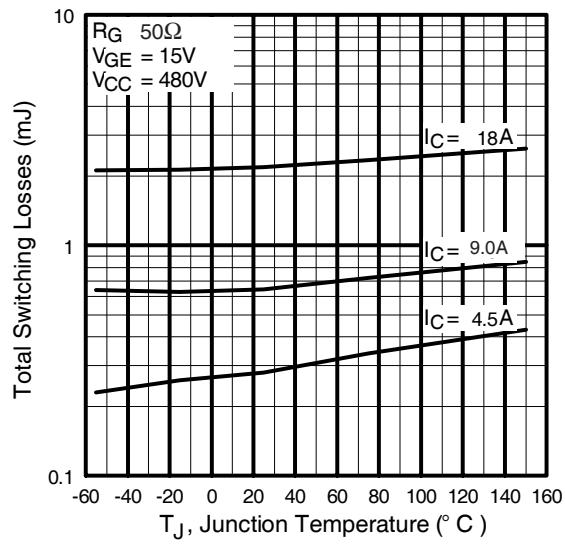


Fig. 10 - Typical Switching Losses vs. Junction Temperature

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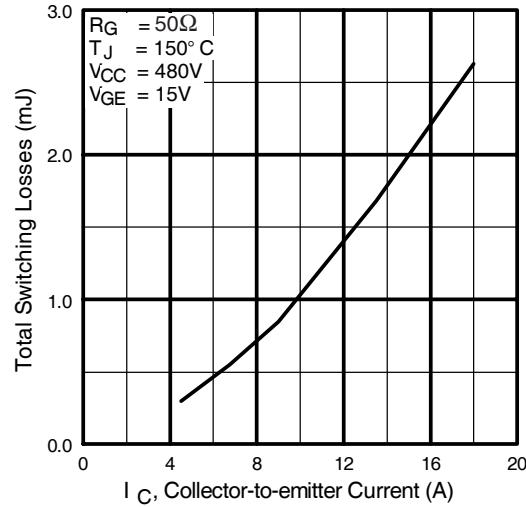


Fig. 11 - Typical Switching Losses vs.
Collector-to-Emitter Current

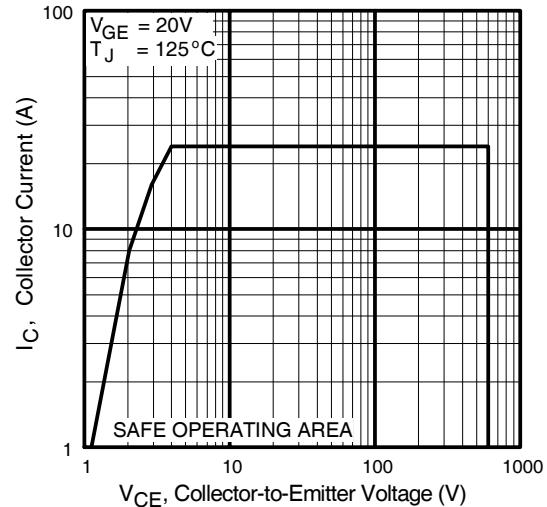


Fig. 12 - Turn-Off SOA

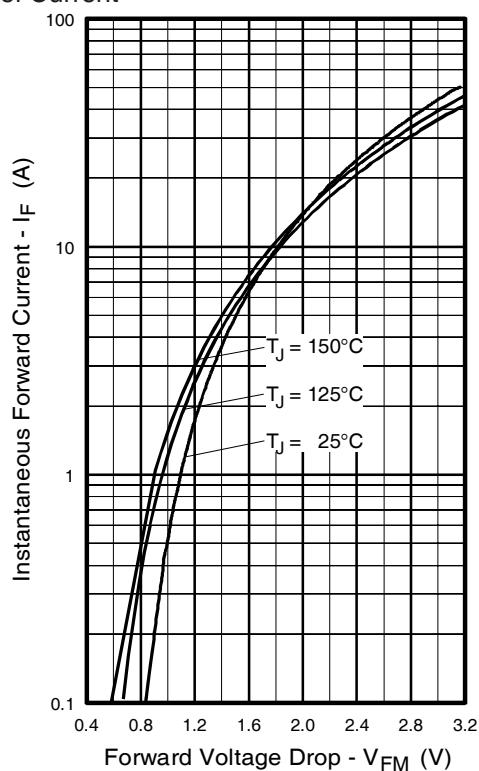


Fig. 13 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

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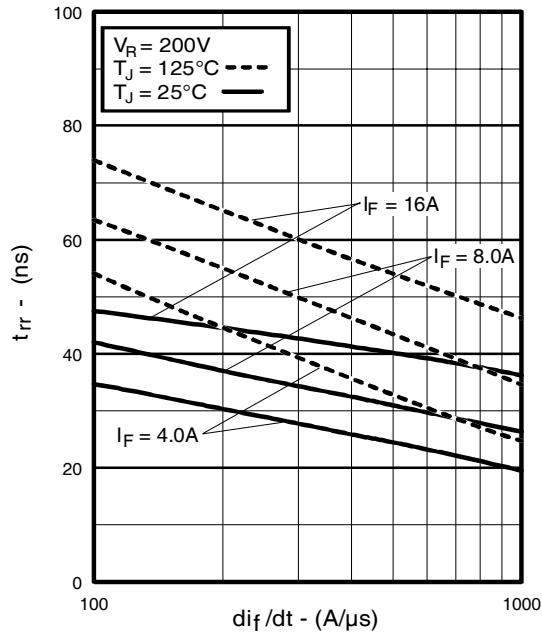


Fig. 14 - Typical Reverse Recovery vs. di_f/dt

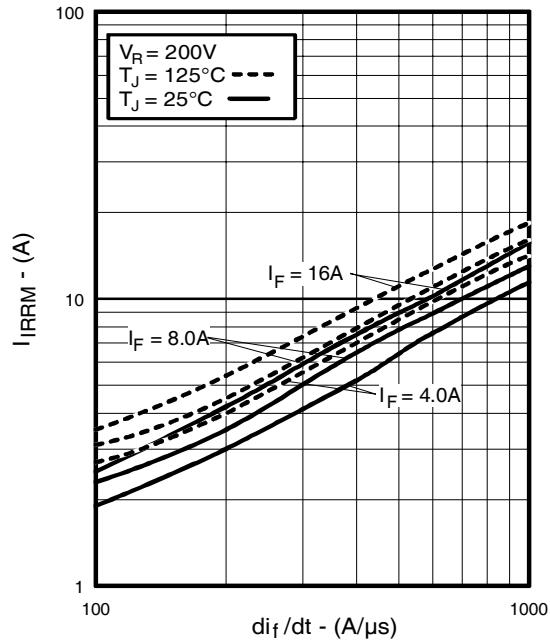


Fig. 15 - Typical Recovery Current vs. di_f/dt

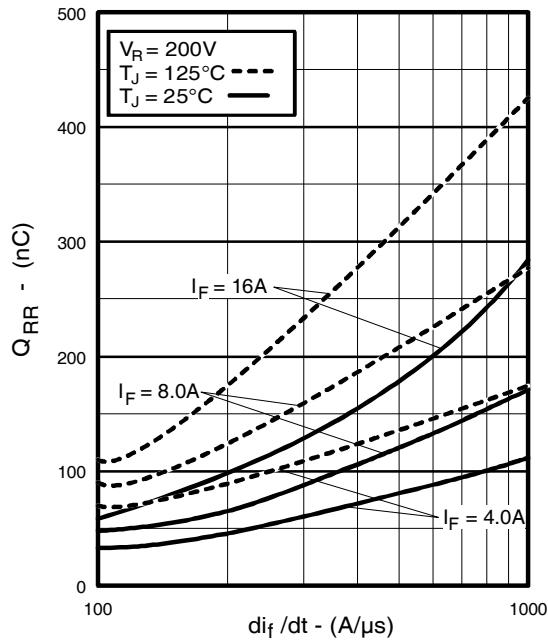


Fig. 16 - Typical Stored Charge vs. di_f/dt

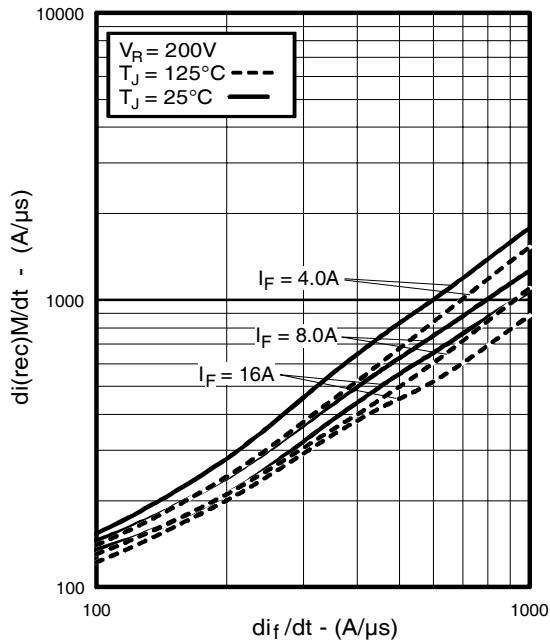


Fig. 17 - Typical $dI_{(rec)}/dt$ vs. di_f/dt

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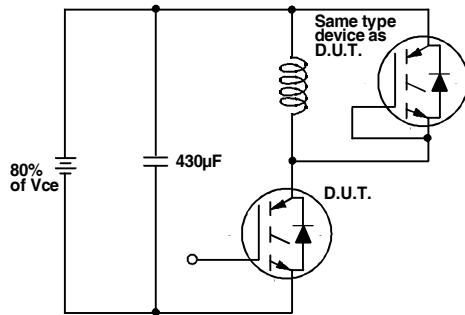


Fig. 18a - Test Circuit for Measurement of I_{LM} , E_{on} , $E_{off(diode)}$, t_{rr} , Q_{rr} , I_{rr} , $t_{d(on)}$, t_r , $t_{d(off)}$, t_f

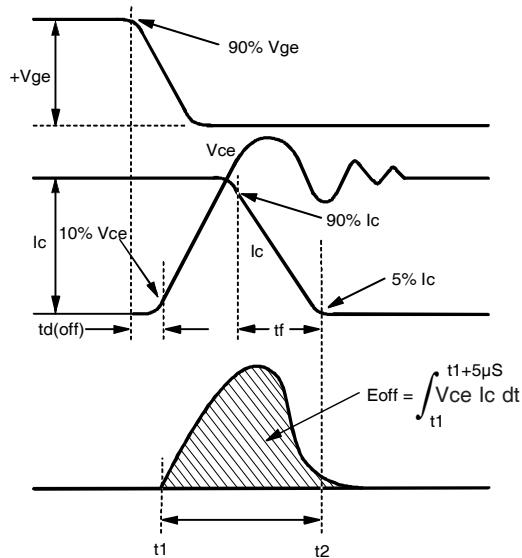


Fig. 18b - Test Waveforms for Circuit of Fig. 18a, Defining E_{off} , $t_{d(off)}$, t_f

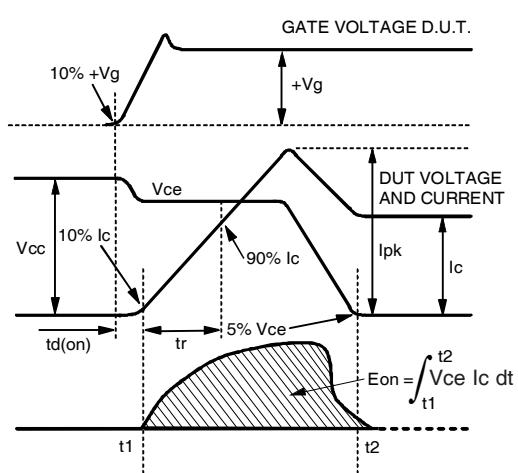


Fig. 18c - Test Waveforms for Circuit of Fig. 18a, Defining E_{on} , $t_{d(on)}$, t_r

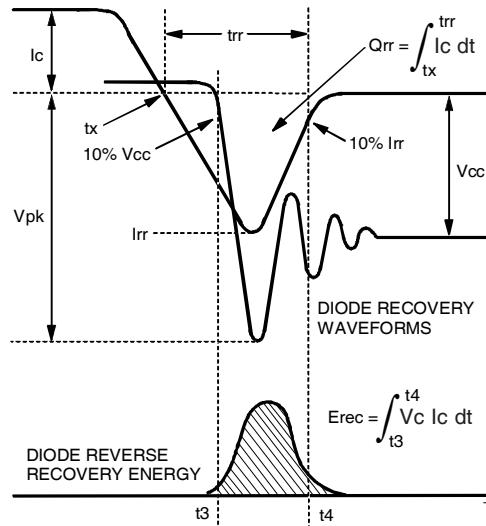


Fig. 18d - Test Waveforms for Circuit of Fig. 18a, Defining E_{rec} , t_{rr} , Q_{rr} , I_{rr}

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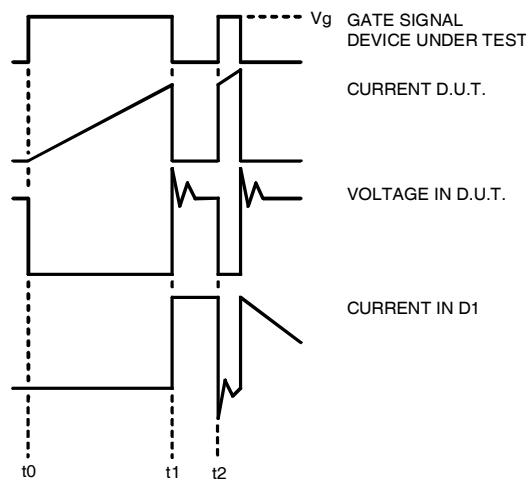


Figure 18e. Macro Waveforms for Figure 18a's Test Circuit

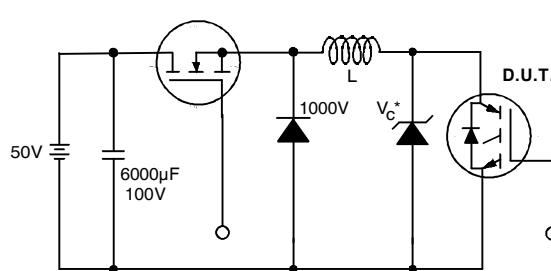


Figure 19. Clamped Inductive Load Test Circuit

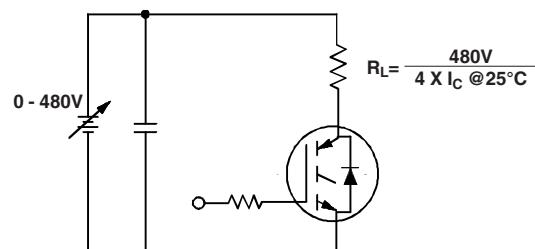


Figure 20. Pulsed Collector Current Test Circuit

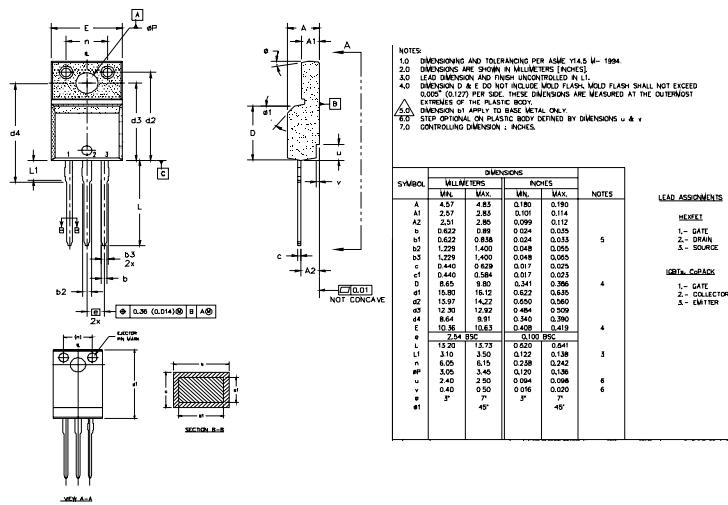
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Notes:

- ① Repetitive rating: $V_{GE}=20V$; pulse width limited by maximum junction temperature (figure 20)
- ② $V_{CC}=80\% (V_{CES})$, $V_{GE}=20V$, $L=10\mu H$, $R_G=50\Omega$ (figure 19)
- ③ Pulse width $\leq 80\mu s$; duty factor $\leq 0.1\%$.
- ④ Pulse width $5.0\mu s$, single shot.

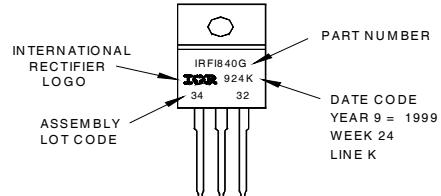
TO-220 Full-Pak Package Outline

Dimensions are shown in millimeters (inches)



TO-220 Full-Pak Part Marking Information

EXAMPLE: THIS IS AN IRFI840G WITH ASSEMBLY LOT CODE 3432 ASSEMBLED ON WW 24 1999 IN THE ASSEMBLY LINE "K"
Note: "P" in assembly line position indicates "Lead-Free"



Data and specifications subject to change without notice.

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